

## SILICON BRIDGE RECTIFIERS

### Features

- ◆ Glass Passivated Chip Junction
- ◆ Reting to 1000V PRV
- ◆ Ideal for printed circuit board
- ◆ Reliable low cost construction utilizing molded plastic
- ◆ technique Plastic material has U/L lammability classification 94V-0
- ◆ Low forward voltage drop,high current capability

### Mechanical Data

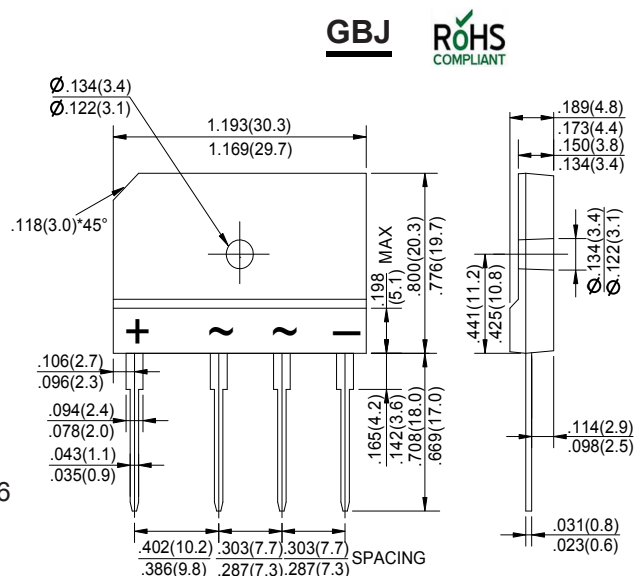
**Case :** JEDEC GBJ Molded plastic body

**Terminals :** Solder plated, solderable per MIL-STD-750,Method 2026

**Polarity :** Polarity symbol marking on body

**Mounting Position :** Any

**Mounting Torque:** 5in-lbs



Dimensions in inches and (millimeters)

### Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	MDD	MDD	MDD	MDD	MDD	MDD	MDD	UNITS
		GBJ10005	GBJ1001	GBJ1002	GBJ1004	GBJ1006	GBJ1008	GBJ1010	
Marking Code									
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum average forward (with heatsink NOTE 2) Rectified current @ $T_c=100^\circ\text{C}$ (without heatsink)	$I_{AV}$	10.0 3.4							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	220							A
Rating for Fusing ( $t < 8.3\text{ms}$ )	$I^2t$	200.86							$\text{A}^2\text{s}$
Maximum forward voltage at 5.0A DC	$V_F$	1.0							V
Maximum DC reverse current at rated DC blocking voltage	$I_R$	$T_A=25^\circ\text{C}$ 10							$\mu\text{A}$
		$T_A=125^\circ\text{C}$ 0.5							$\text{mA}$
Typical Junction Capacitance (Note 1)	$C_J$	55							$\text{pF}$
Typical Thermal Resistance (Note 2)	$R_{\theta JA}$	1.8							$^\circ\text{C/W}$
Operating junction temperature range	$T_J$	-55 to +150							$^\circ\text{C}$
storage temperature range	$T_{STG}$	-55 to +150							$^\circ\text{C}$

NOTES: 1. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

2. Device mounted on 75mm\*75mm\*1.6mm Cu plate heatsink.

3. The typical data above is for reference only.

## Ratings And Characteristic Curves

FIG.1-FORWARD CURRENT DERATING CURVE

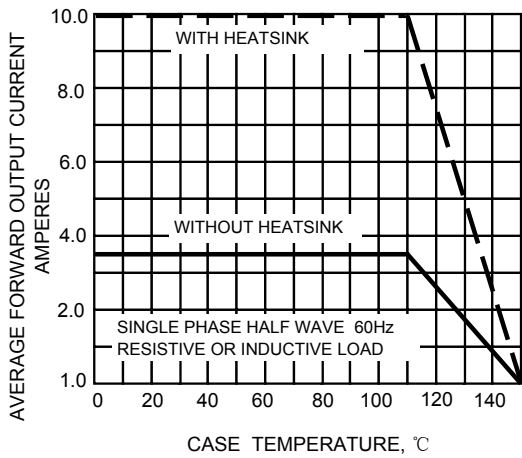


FIG.2-MAXMUN NON-REPETITIVE SURGE CURRENT

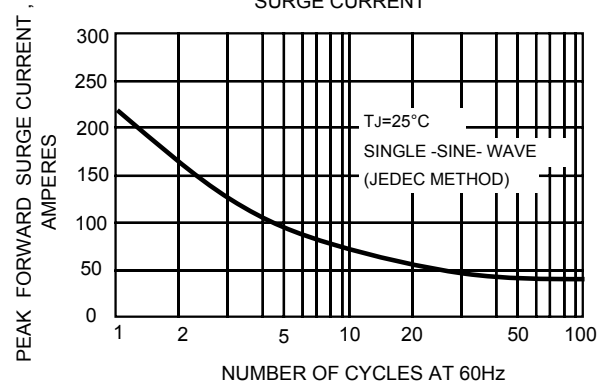


FIG.3-TYPICAL JUNCTION CAPACITANCE

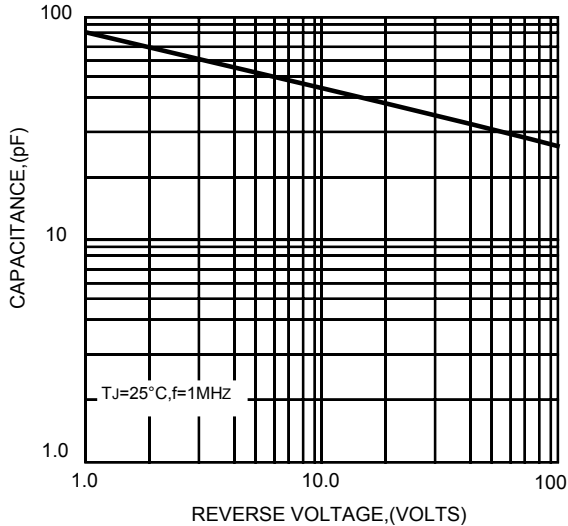


FIG.4-TYPICAL FORWARD CHARACTERISTICS

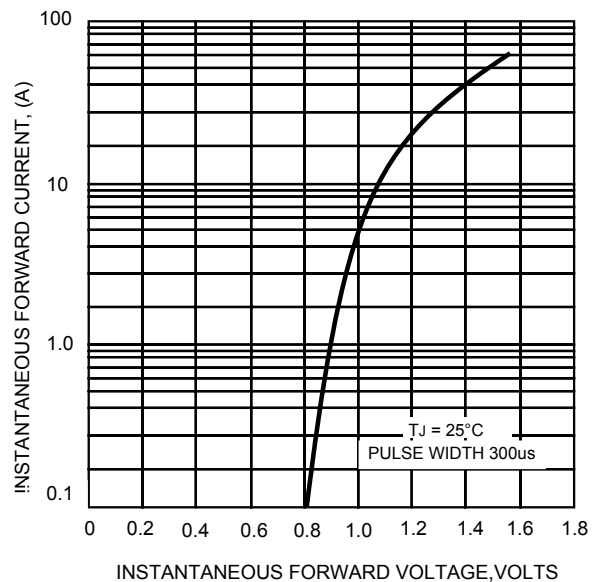
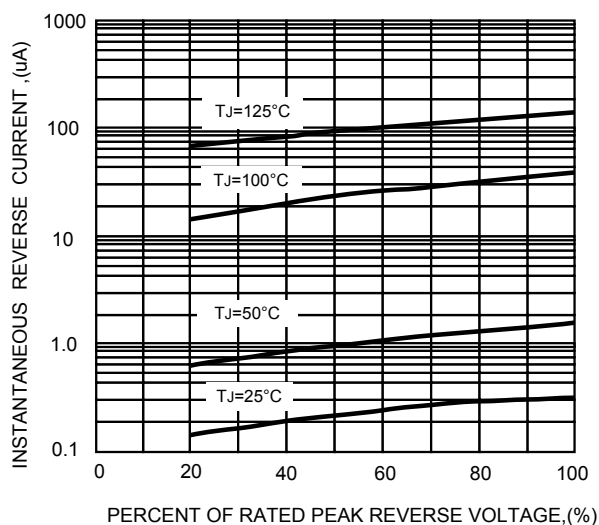


FIG.5-TYPICAL REVERSE CHARACTERISTICS



The curve above is for reference only.



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